

## LV05 NO CLEAN FLUX CORED WIRE TDS

#### **FEATURES**

- Optimized for Robotic Soldering
- Excellent Wetting Properties
- Excellent Thermal Transfer
- REACH and RoHS Compliant\*
- ROL1 per Current J-STD-004

### **DESCRIPTION**

LV05 no clean flux cored wire has been specifically engineered for high volume – high speed electronic assembly. Hand soldering operations benefit from LV05 with fast wetting and low odor resulting in high operator satisfaction. Consistent soldering performance makes LV05 ideal for automated soldering operations. LV05 leaves minimal residues that do not require cleaning and is suitable for automotive and military applications.

#### STANDARD AVALIABILITY

LV05 Cored Wire is available in SAC305 alloy in the diameters below. Other diameters may be available upon request.

### **APPLICATION**

Solder iron tip temperatures are typically between 370° - 425°C (700° - 800°F). Higher or lower temperatures may be used depending on equipment and materials in use.



### **HANDLING & STORAGE**

TIME	TEMPERATURE
7 Years	< 85°F (< 29°C)

Store cored wire in a clean, dry area away from moisture and sunlight. Do not freeze this product.

### **CLEANING**

LV05 residues do not require cleaning. However, in applications when cleaning is required, contact AIM for compatibility recommendations.

### **SAFETY**

Use with adequate ventilation and proper personal protective equipment. Refer to the accompanying Safety Data Sheet for any specific emergency information. Do not dispose of any hazardous materials in non-approved containers.

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# **TECHNICAL DATA SHEET**



### **TEST DATA SUMMARY**

NAME	TEST METHOD		RESULTS	
IPC Flux Classification	J-STD-004	ROL0		
IPC Flux Classification	J-STD-004 Current Rev 3.3.1	ROL1		
NAME	TEST METHOD	RESULTS	IMAGE	
Copper Mirror	J-STD-004 Current Rev 3.4.1.1 IPC-TM-650 2.3.32	LOW	CONTROL	
Corrosion	J-STD-004 Current Rev 3.4.1.2 IPC-TM-650 2.6.15	PASS	Before After	
Quantitative Halides	J-STD-004 Current Rev 3.4.1.3 IPC-TM-650 2.3.28.1	Br: 0.28% Cl: 0.00%		
Qualitative Halides, Silver Chromate	J-STD-004 Current Rev 3.5.1.1 IPC-TM-650 2.3.33	PASS		
Qualitative Halides, Fluoride Spot	J-STD-004 Current Rev 3.5.1.2 IPC-TM-650 2.3.35.1	No Fluoride		
Surface Insulation Resistance	J-STD-004 Current Rev 3.4.1.4 IPC-TM-650 2.6.3.7	PASS	13 12 11 10 10 10 10 10 10 10 10 10 10 10 10	

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